

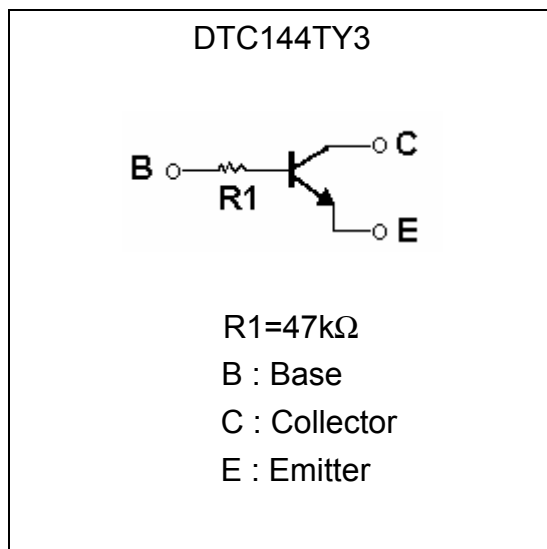
NPN Digital Transistors (Built-in Resistor)

DTC144TY3

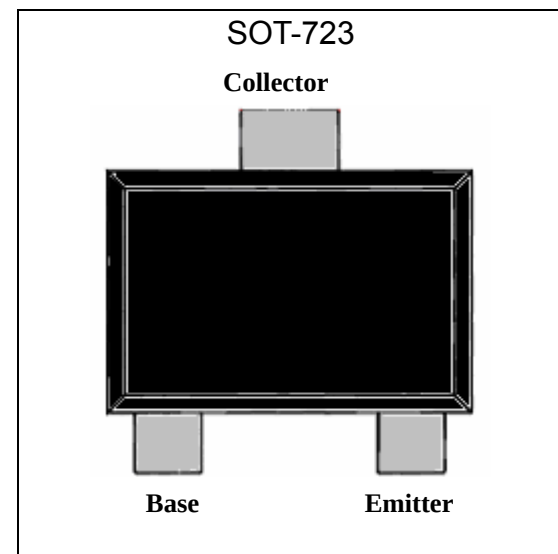
Features

- Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see equivalent circuit).
- The bias resistors consist of thin-film resistors with complete isolation to allow negative biasing of the input. They also have the advantage of almost completely eliminating parasitic effects.
- Only the on/off conditions need to be set for operation, making device design easy.
- Complements the DTA144TY3
- Pb-free lead plating package

Equivalent Circuit



Outline



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V _{CB0}	50	V
Collector-Emitter Voltage	V _{CEO}	50	V
Emitter-Base Voltage	V _{EB0}	5	V
Collector Current	I _C	100	mA
Power Dissipation	P _d	150	mW
Thermal Resistance, Junction to Ambient	R _{θJA}	833	°C/W
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55 ~ +150	°C

**Characteristics (Ta=25°C)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Collector-Base Breakdown Voltage	V _{CB0}	50	-	-	V	I _C =50μA
Collector-Emitter Breakdown Voltage	V _{CEO}	50	-	-	V	I _C =1mA
Emitter-Base Breakdown Voltage	V _{EB0}	5	-	-	V	I _E =50μA
Collector-Base Cutoff Current	I _{CB0}	-	-	0.5	μA	V _{CB} =50V
Emitter-Base Cutoff Current	I _{EB0}	-	-	0.5	μA	V _{EB} =4V
Collector-Emitter Saturation Voltage	V _{CE(sat)}	-	-	0.3	V	I _C =5mA, I _B =0.5mA
DC Current Gain	h _{FE}	100	-	600	-	V _{CE} =5V, I _C =1mA
Input Resistance	R _i	32.9	47	61.1	kΩ	-
Transition Frequency	f _T	-	250	-	MHz	V _{CE} =10V, I _C =5mA, f=100MHz *

* Transition frequency of the device

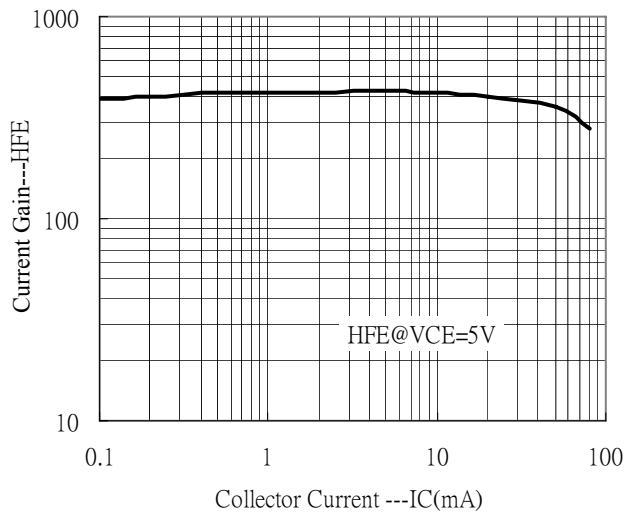
Ordering Information

Device	Package	Shipping	Marking
DTC144TY3	SOT-723 (Pb-free lead plating package)	8000 pcs / Tape & Reel	8T

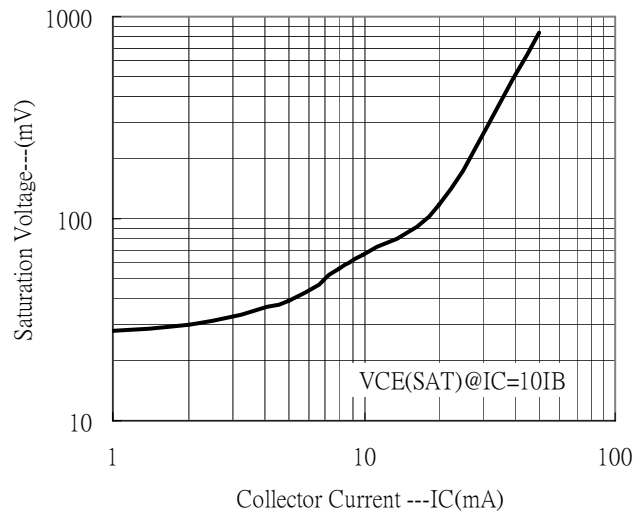


Typical Characteristics

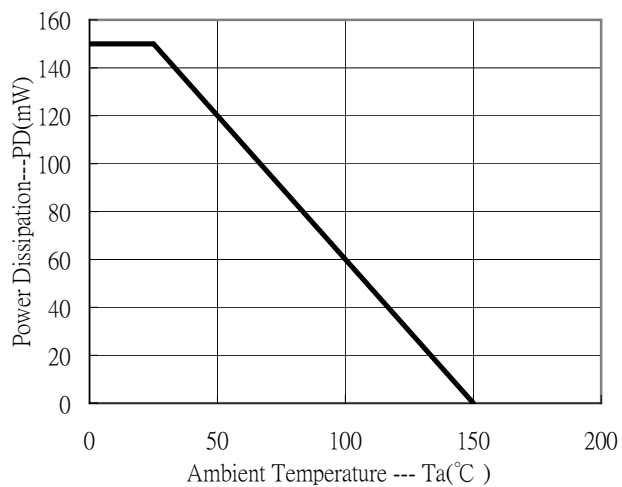
Current Gain vs Collector Current



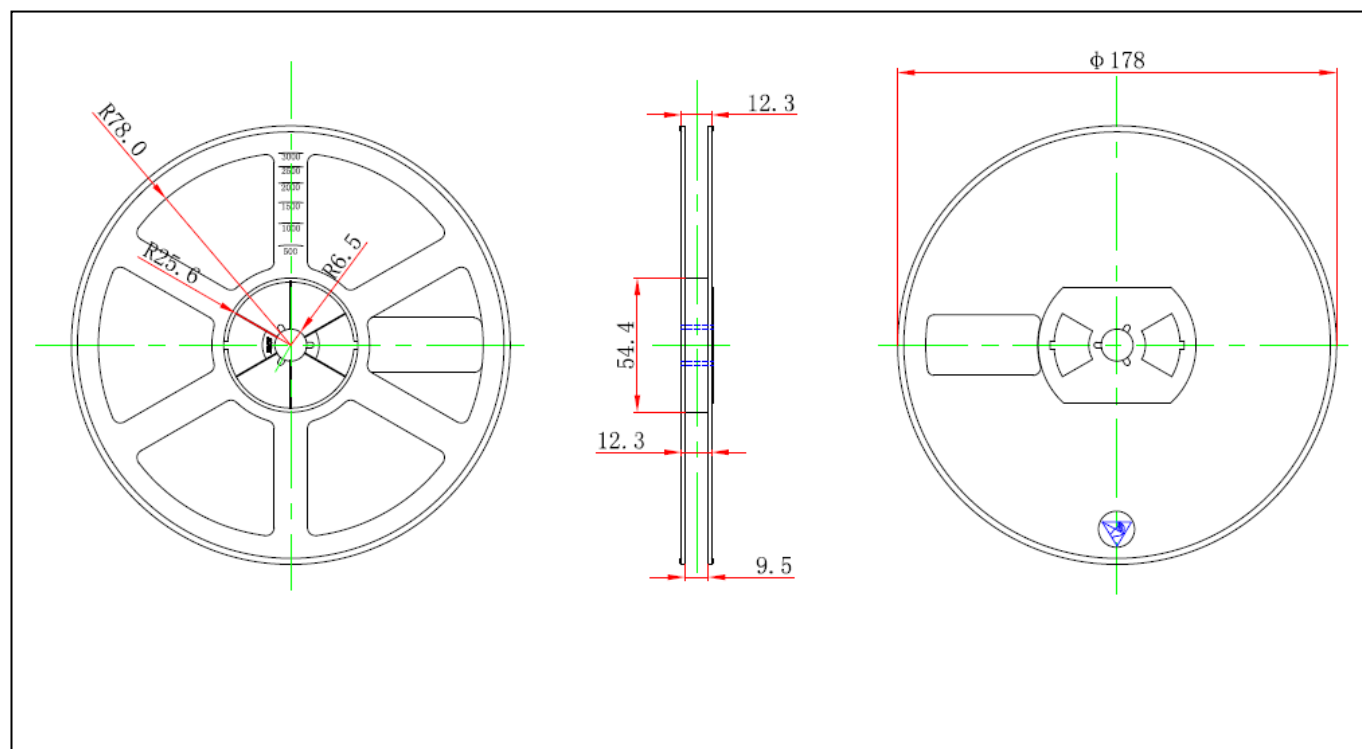
Saturation Voltage vs Collector Current



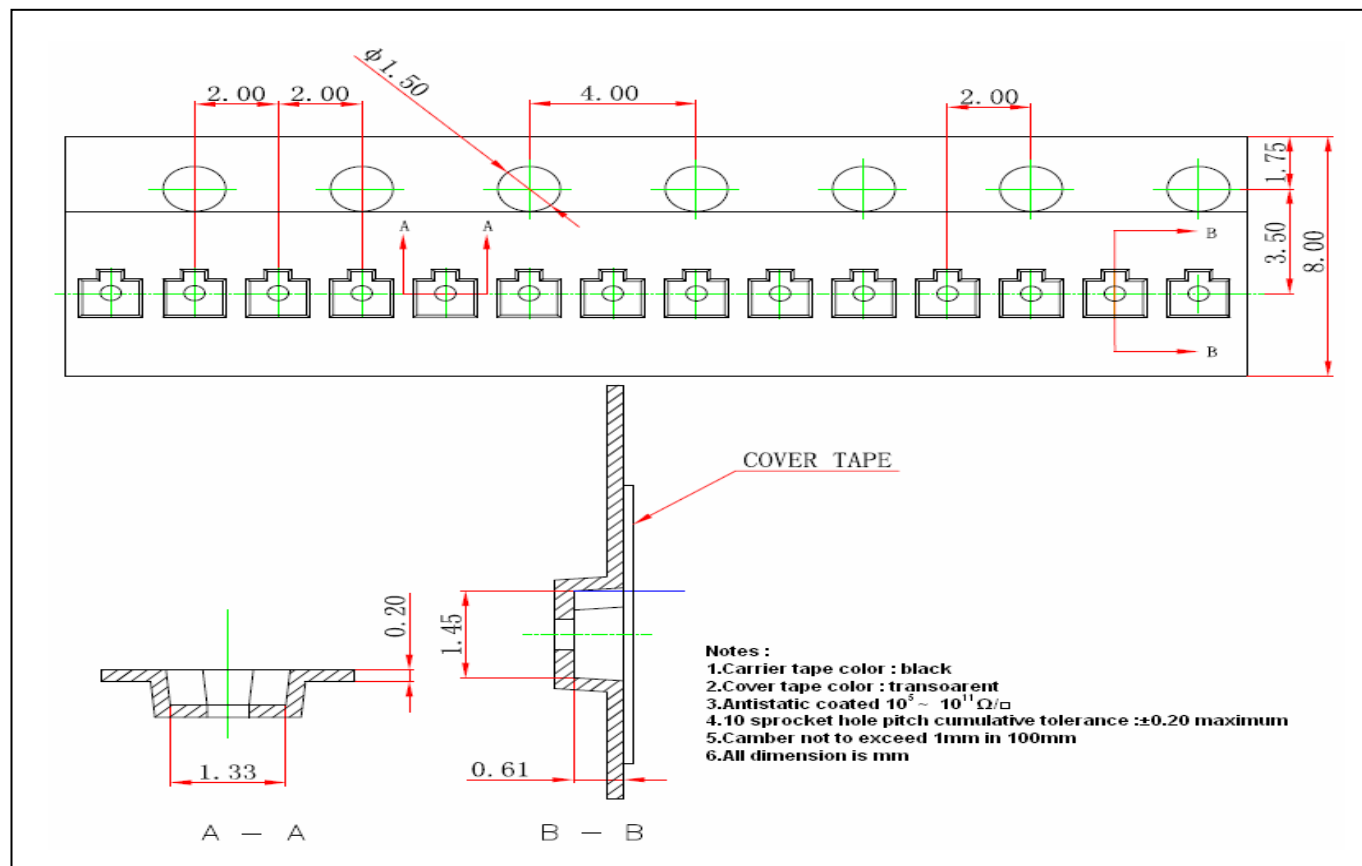
Power Derating Curve



Reel Dimension



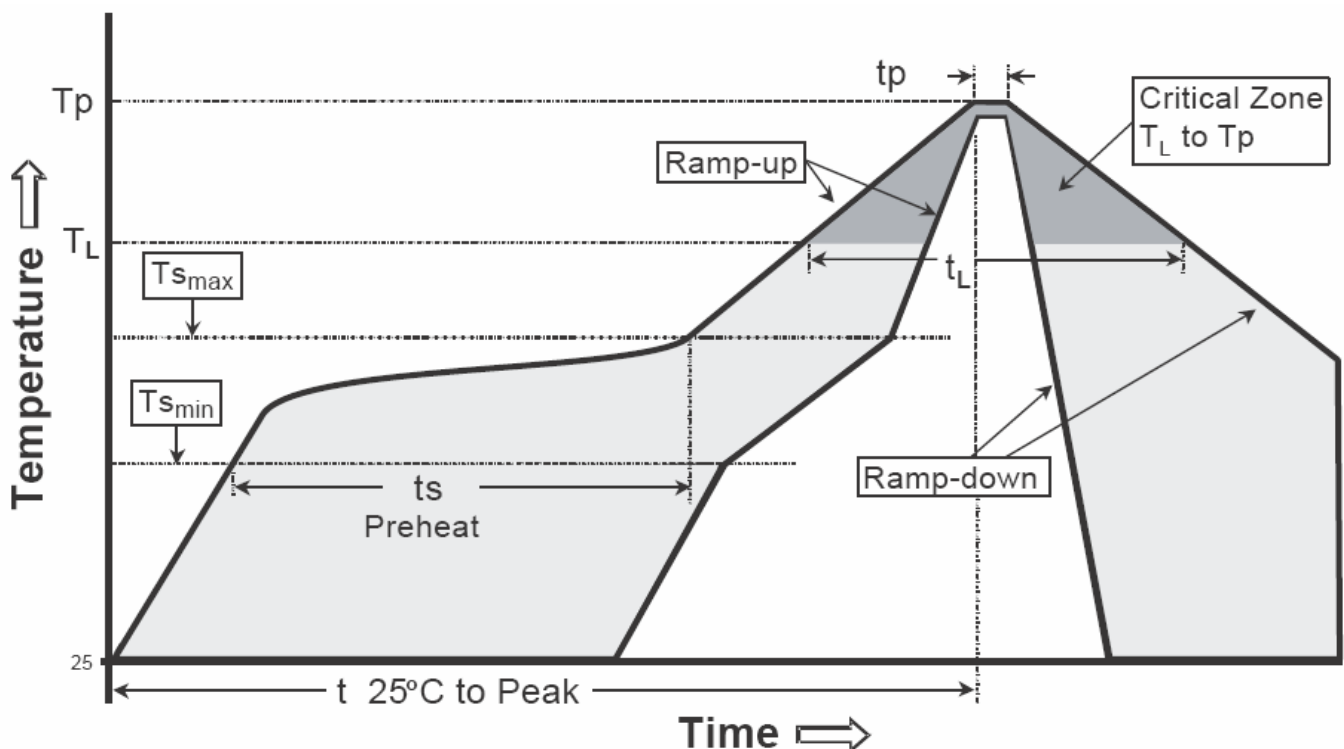
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

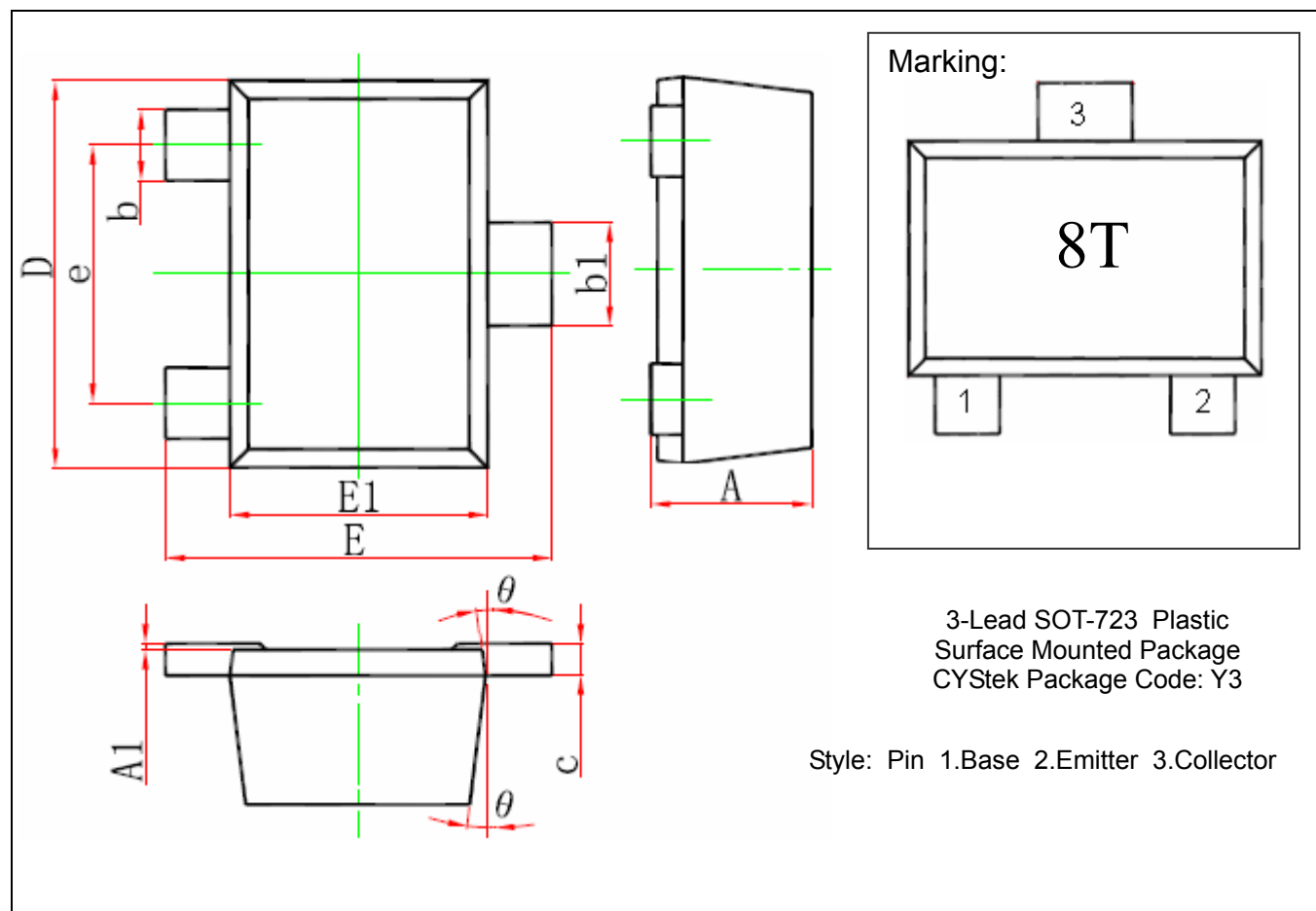
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (Tl)	183°C	217°C
- Time (tL)	60-150 seconds	60-150 seconds
Peak Temperature(Tp)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-723 Dimension



*Typical

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.000	0.500	0.000	0.020	D	1.150	1.250	0.045	0.049
A1	0.000	0.050	0.000	0.002	E	1.150	1.250	0.045	0.049
b	0.170	0.270	0.007	0.011	E1	0.750	0.850	0.030	0.033
b1	0.270	0.370	0.011	0.015	e	0.800*		0.031*	
c	0.000	0.150	0.000	0.006	θ	7° REF		7° REF	

Notes: 1.Controlling dimension: millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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